

CDCV850 2.5-V PHASE LOCK LOOP CLOCK DRIVER WITH 2-LINE SERIAL INTERFACE

SCAS647D – OCTOBER 2000 – REVISED APRIL 2013

- **Phase-Lock Loop Clock Driver for Double Data-Rate Synchronous DRAM Applications**
- **Spread Spectrum Clock Compatible**
- **Operating Frequency: 60 to 140 MHz**
- **Low Jitter (cyc–cyc): ± 75 ps**
- **Distributes One Differential Clock Input to Ten Differential Outputs**
- **Two-Line Serial Interface Provides Output Enable and Functional Control**
- **Outputs Are Put Into a High-Impedance State When the Input Differential Clocks Are <20 MHz**
- **48-Pin TSSOP Package**
- **Consumes <250- μ A Quiescent Current**
- **External Feedback Pins (FBIN, $\overline{\text{FBIN}}$) Are Used to Synchronize the Outputs to the Input Clocks**

description

The CDCV850 is a high-performance, low-skew, low-jitter zero delay buffer that distributes a differential clock input pair (CLK, $\overline{\text{CLK}}$) to ten differential pairs of clock outputs (Y[0:9], $\overline{\text{Y}}[0:9]$) and one differential pair of feedback clock outputs (FBOUT, $\overline{\text{FBOUT}}$). The clock outputs are controlled by the clock inputs (CLK, $\overline{\text{CLK}}$), the feedback clocks (FBIN, $\overline{\text{FBIN}}$), the 2-line serial interface (SDATA, SCLK), and the analog power input (AV_{DD}). A two-line serial interface can put the individual output clock pairs in a high-impedance state. When the AV_{DD} terminal is tied to GND, the PLL is turned off and bypassed for test purposes.

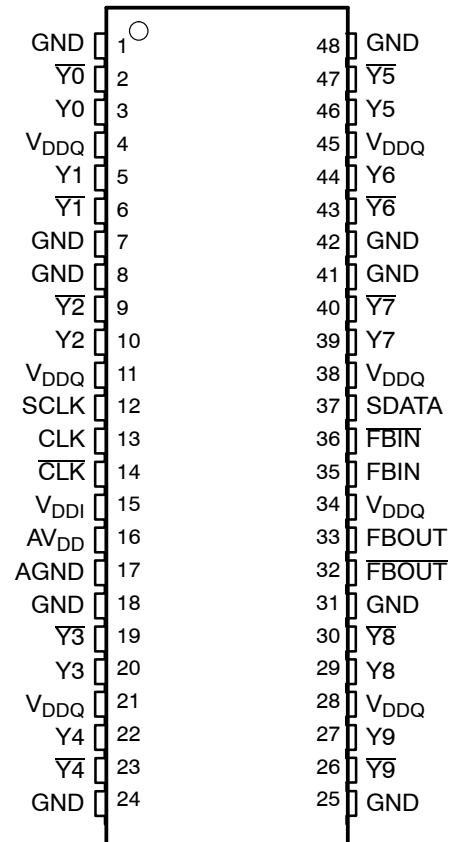
The device provides a standard mode (100 Kbits/s) 2-line serial interface for device control. The implementation is as a slave/receiver. The device address is specified in the 2-line serial device address table. Both of the 2-line serial inputs (SDATA and SCLK) provide integrated pullup resistors (typically 100 k Ω).

Two 8-bit, 2-line serial registers provide individual enable control for each output pair. All outputs default to enabled at powerup. Each output pair can be placed in a high-impedance mode, when a low-level control bit is written to the control register. The registers must be accessed in sequential order (i.e., random access of the registers not supported). The serial interface circuit can be supplied with either 2.5 V or 3.3 V (at VDDI) in applications where this programming option is not required (after power up, all output pairs will then be enabled).

When the input frequency falls below a suggested detection frequency that is below 20 MHz (typically 10 MHz), the output pairs are put into a high-impedance condition, the PLL is shut down, and the device will enter a low power mode. The CDCV850 is also able to track spread spectrum clocking for reduced EMI.

Since the CDCV850 is based on PLL circuitry, it requires a stabilization time to achieve phase-lock of the PLL. This stabilization time is required following power up, as well as changes to various 2-line serial registers that affect the PLL. The CDCV850 is characterized in a temperature range from -40°C to 85°C .

DGG PACKAGE
(TOP VIEW)



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AVAILABLE OPTIONS

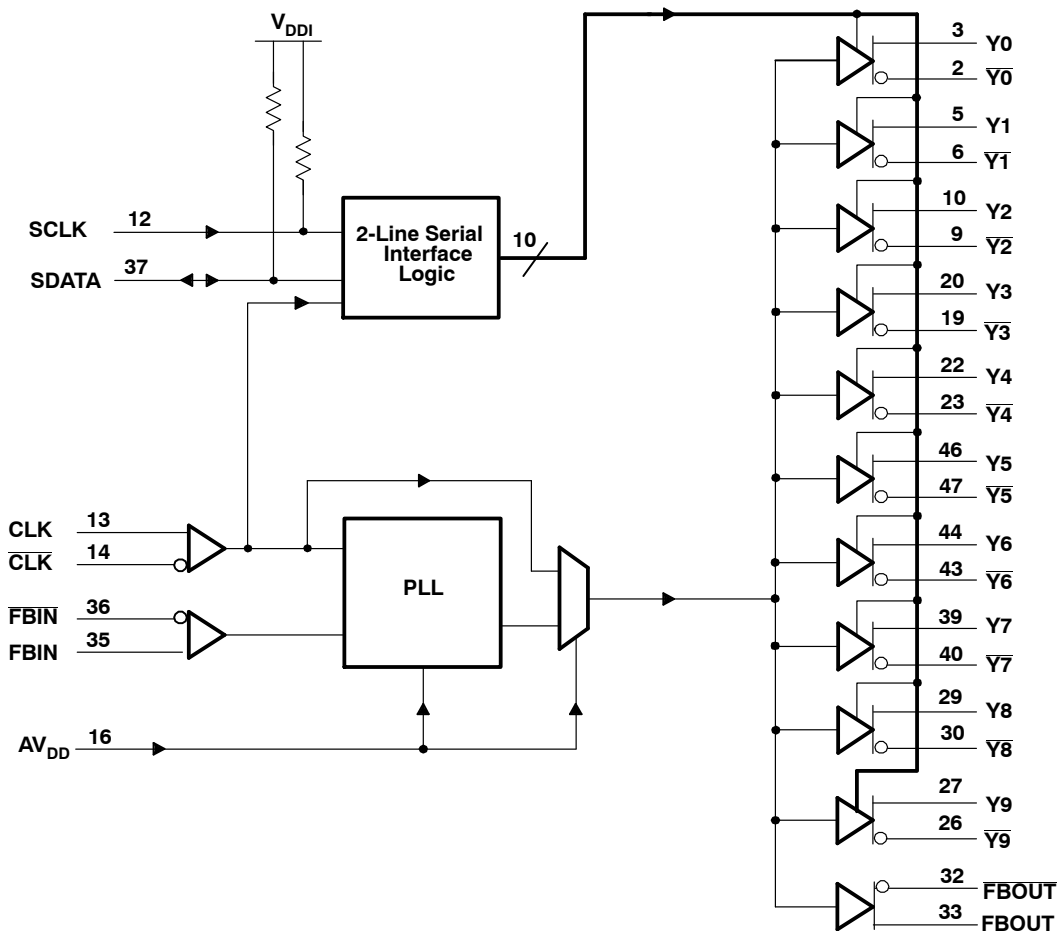
T _A	PACKAGED DEVICES
	TSSOP (DGG)
-40°C to 85°C	CDCV850DGG

FUNCTION TABLE (Select Functions)

INPUTS			OUTPUTS [†]				PLL
AV _{DD}	CLK	CLK	Y[0:9]	Y[0:9]	FBOUT	FBOUT	
GND	L	H	L	H	L	H	Bypassed/Off
GND	H	L	H	L	H	L	Bypassed/Off
2.5 V (nom)	L	H	L	H	L	H	On
2.5 V (nom)	H	L	H	L	H	L	On
2.5 V (nom)	<20 MHz	<20 MHz	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Off

[†] Each output pair (except FBOUT, FBOUT) can be put into a high-impedance state through the 2-line serial interface.

functional block diagram



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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
AGND	17		Ground for 2.5-V analog supply
AV _{DD}	16		2.5-V analog supply
CLK, $\overline{\text{CLK}}$	13, 14	I	Differential clock input
FBIN, $\overline{\text{FBIN}}$	35, 36	I	Feedback differential clock input
FBOU _T , $\overline{\text{FBOU}}$	32, 33	O	Feedback differential clock output
GND	1, 7, 8, 18, 24, 25, 31, 41, 42, 48		Ground
SCLK	12	I	Clock input for 2-line serial interface
SDATA	37	I/O	Data input/output for 2-line serial interface
V _{DDQ}	4, 11, 21, 28, 34, 38, 45		2.5-V supply
V _{DDI}	15	I	2.5-V or 3.3-V supply for 2-line serial interface
Y[0:9]	3, 5, 10, 20, 22, 27, 29, 39, 44, 46	O	Buffered output copies of input clock, CLK
$\overline{\text{Y}}$ [0:9]	2, 6, 9, 19, 23, 26, 30, 40, 43, 47	O	Buffered output copies of input clock, $\overline{\text{CLK}}$

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absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage range:	V_{DDQ}, AV_{DD}	–0.5 V to 3.6 V
	V_{DDI}	–0.5 V to 4.6 V
Input voltage range:	V_I (except SCLK and SDATA) (see Notes 1 and 2)	–0.5 V to $V_{DDQ} + 0.5$ V
	V_I (SCLK, SDATA) (see Notes 1 and 2)	–0.5 V to $V_{DDI} + 0.5$ V
Output voltage range:	V_O (except SDATA) (see Notes 1 and 2)	–0.5 V to $V_{DDQ} + 0.5$ V
	V_O (SDATA) (see Notes 1 and 2)	–0.5 V to $V_{DDQ} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DDQ}$)		±50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DDQ}$)		±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{DDQ})		±50 mA
Package thermal impedance, θ_{JA} (see Note 3): DGG package		89°C/W
Storage temperature range T_{stg}		–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. This value is limited to 3.6 V maximum.
 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

		MIN	TYP	MAX	UNIT
Supply voltage	V_{DDQ}, AV_{DD}	2.3		2.7	V
	V_{DDI} (see Note 5)	2.3		3.6	
Low level input voltage, V_{IL}	CLK, $\overline{\text{CLK}}$, HCSL Buffer only		0	0.24	V
	CLK, $\overline{\text{CLK}}$	–0.3		$V_{DDQ} - 0.4$	
	FBIN, $\overline{\text{FBIN}}$			$V_{DDQ}/2 - 0.18$	
	SDATA, SCLK			$0.3 \times V_{DDI}$	
High level input voltage, V_{IH}	CLK, $\overline{\text{CLK}}$, HCSL Buffer only	0.66	0.71		V
	CLK, $\overline{\text{CLK}}$	0.4		$V_{DDQ} + 0.3$	
	FBIN, $\overline{\text{FBIN}}$	$V_{DDQ}/2 + 0.18$			
	SDATA, SCLK	$0.7 \times V_{DDI}$			
DC input signal voltage (see Note 6)		–0.3		$V_{DDQ} + 0.3$	V
Differential input signal voltage, V_{ID} (see Note 7)	DC CLK, FBIN	0.36		$V_{DDQ} + 0.6$	V
	AC CLK, FBIN	0.2		$V_{DDQ} + 0.6$	
Input differential pair cross-voltage, V_{IX} (see Note 8)		$0.45 \times (V_{IH} - V_{IL})$		$0.55 \times (V_{IH} - V_{IL})$	V
High-level output current, I_{OH}				–12	mA
Low-level output current, I_{OL}				12	V
		SDATA		3	mA
Input slew rate, SR (see Figure 8)		1		4	V/ns
SSC modulation frequency		30		33.3	kHz
SSC clock input frequency deviation		0		–0.50	kHz
Operating free-air temperature, T_A		–40		85	°C

- NOTES: 4. Unused inputs must be held high or low to prevent them from floating.
 5. All devices on the serial interface bus, with input levels related to V_{DDI} , must have one common supply line to which the pullup resistor is connected to.
 6. DC input signal voltage specifies the allowable dc execution of differential input.
 7. Differential input signal voltage specifies the differential voltage $|V_{TR} - V_{CP}|$ required for switching, where V_{TR} is the true input level and V_{CP} is the complementary input level.
 8. Differential cross-point voltage is expected to track variations of VCC and is the voltage at which the differential signals must be crossing.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{IK}	Input voltage	All inputs	V _{DDQ} = 2.3 V, I _I = -18 mA			-1.2	V
V _{OH}	High-level output voltage		V _{DDQ} = min to max, I _{OH} = -1 mA	V _{DDQ} - 0.1			V
			V _{DDQ} = 2.3 V, I _{OH} = -12 mA	1.7			
V _{OL}	Low-level output voltage		V _{DDQ} = min to max, I _{OL} = 1 mA			0.1	V
			V _{DDQ} = 2.3 V, I _{OL} = 12 mA			0.6	
		SDATA	V _{DDI} = 3.0 V, I _{OL} = 3 mA			0.4	
I _{OH}	High-level output current		V _{DDQ} = 2.3 V, V _O = 1 V	-18	-32		mA
I _{OL}	Low-level output current		V _{DDQ} = 2.3 V, V _O = 1.2 V	26	35		mA
V _O	Output voltage swing		For load condition see Figure 3	1.1		V _{DDQ} - 0.4	V
V _{OX}	Output differential cross voltage			V _{DDQ} /2 - 0.2	V _{DDQ} /2	V _{DDQ} /2 + 0.2	V
I _I	Input current	SDATA, SCLK	V _{DDQ} = 3.6 V, V _I = 0 V to 3.6 V			+10/-50	μA
		CLK, FBIN	V _{DDQ} = 2.7 V, V _I = 0 V to 2.7 V			±10	μA
I _{OZ}	High-impedance-state output current		V _{DDQ} = 2.7 V, V _O = V _{DDQ} or GND			±10	μA
I _{DDPD}	Power-down current on V _{DDQ} + AV _{DD}		CLK at 0 MHz; Σ of I _{DD} and A _{DD}		150	250	μA
	Power down current on V _{DDI}		CLK at 0 MHz; V _{DDQ} = 3.6 V		3	20	μA
I _{DD}	Dynamic current on V _{DDQ}		V _{DDQ} = 2.7 V, f _O = 100 MHz All differential output pairs are terminated with 120 Ω / C _L = 4 pF		205	230	mA
A _{I(DD)}	Supply current on AV _{DD}		AV _{DD} = 2.7 V, f _O = 100 MHz		4	6	mA
I _{DDI}	Supply current on V _{DDI}		V _{DDI} = 3.6 V, SCLK and SDATA = 3.6 V		1	2	mA
C _I	Input capacitance		V _{DDQ} = 2.5 V, V _I = V _{DDQ} or GND	2	2.5	3	pF
C _O	Output capacitance		V _{DDQ} = 2.5 V, V _O = V _{DDQ} or GND	2.5	3	3.5	pF

† All typical values are at respective nominal V_{DDQ}.

‡ The value of V_{OC} is expected to be |V_{TR} + V_{CP}]/2. In case of each clock directly terminated by a 120-Ω resistor, where V_{TR} is the true input signal voltage and V_{CP} is the complementary input signal voltage (see Figure 3).

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timing requirements over recommended ranges of supply voltage and operating free-air temperature

	MIN	MAX	UNIT
$f_{(CLK)}$ Clock frequency	60	140	MHz
Input clock duty cycle	40%	60%	
Stabilization time [†]		10	μ s

[†] Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLK. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable. This parameter does not apply for input modulation under SSC application.

timing requirements for the 2-line serial interface over recommended ranges of operating free-air temperature and VDDI from 3.3 V to 3.6 V (see Figure 10)

	MIN	MAX	UNIT
$f_{(SCLK)}$ SCLK frequency		100	kHz
$t_{(BUS)}$ Bus free time	4.7		μ s
$t_{su}(START)$ START setup time [†]	4.7		μ s
$t_h(START)$ START hold time [†]	4.0		μ s
$t_w(SCLL)$ SCLK low pulse duration	4.7		μ s
$t_w(SCLH)$ SCLK high pulse duration	4.0		μ s
$t_r(SDATA)$ SDATA input rise time		1000	ns
$t_f(SDATA)$ SDATA input fall time		300	ns
$t_{su}(SDATA)$ SDATA setup time	250		ns
$t_h(SDATA)$ SDATA hold time	0		ns
$t_{su}(STOP)$ STOP setup time	4		μ s

[†] This conforms to I2C specification, version 2.1.



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switching characteristics over recommended ranges of operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
t_{pd}	Propagation delay time	Test mode/CLK to any output		4		ns	
t_{PHL}	High-to low-level propagation delay time	SCLK to SDATA (acknowledge)		500 [†]		ns	
t_{en}	Output enable time	Test mode/SDATA to Y-output		85		ns	
t_{dis}	Output disable time	Test mode/SDATA to Y-output		35		ns	
$t_{jit(per)}$	Jitter (period), See Figure 6	100/133 MHz	-30		30	ps	
$t_{jit(cc)}$	Jitter (cycle-to-cycle), See Figure 3	100/133 MHz	-30		30	ps	
$t_{jit(hper)}$	Half-period jitter, See Figure 7	100/133 MHz	-75		75	ps	
$t_{(\phi)}$	Static phase offset, See Figure 4a	0°C to 85°C	100 MHz/VID on CLK = 0.71 V [‡]		-120	120	ps
			100 MHz/VID on CLK = 0.59 V [§]		-50	160	
			100 MHz/VID on CLK = 0.82 V [¶]		-170	70	
			133 MHz/VID on CLK = 0.71 V [¶]		-50	180	
		-40°C to 85°C	100 MHz/VID on CLK = 0.71 V [‡]		-160	80	ps
			100 MHz/VID on CLK = 0.59 V [§]		-90	120	
			100 MHz/VID on CLK = 0.82 V [¶]		-210	30	
			133 MHz/VID on CLK = 0.71 V [¶]		-80	150	
$td_{(\phi)}$ [#]	Dynamic phase offset, SSC on, See Figure 4b and Figure 9	100 MHz/VID on CLK = 0.71 V [‡]		-190	190	ps	
		133 MHz/VID on CLK = 0.71 V [‡]		-140	140	ps	
	Dynamic phase offset, SSC off, See Figure 4b	100 MHz/VID on CLK = 0.71 V [‡]		-160	160	ps	
		133 MHz/VID on CLK = 0.71 V [‡]		-130	130	ps	
$t_{slr(o)}$	Output clock slew rate, terminated with 120Ω/14 pF, See Figures 1 and 8		1		2	V/ns	
$t_{slr(o)}$	Output clock slew rate, terminated with 120Ω/4 pF, See Figures 1 and 8		1		3	V/ns	
$t_{sk(o)}$	Output skew, See Figure 5				75	ps	
	SSC modulation frequency		30		33.3	kHz	
	SSC clock input frequency deviation		0.00		-0.50	%	

[†] This time is for a PLL frequency of 100 MHz.

[‡] According CK00 spec: $6 \times I_{ref}$ at 50 Ω and $R_{ref} = 475 \Omega$

[§] According CK00 spec: $5 \times I_{ref}$ at 50 Ω and $R_{ref} = 475 \Omega$

[¶] According CK00 spec: $7 \times I_{ref}$ at 50 Ω and $R_{ref} = 475 \Omega$

[#] The parameter is assured by design but cannot be 100% production tested.

^{||} All differential output pins are terminated with 120 Ω/4 pF

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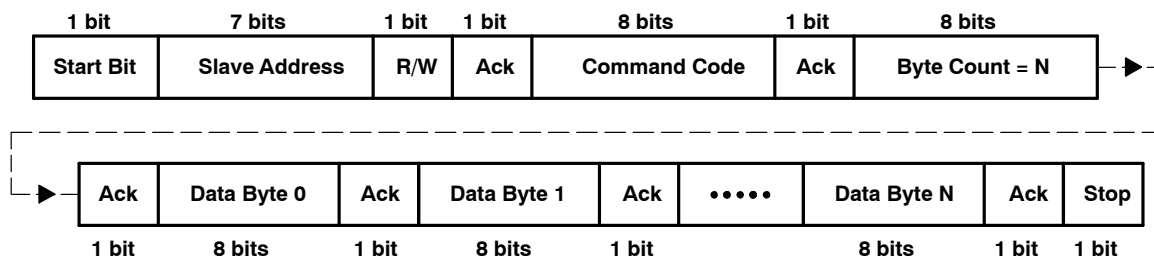
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2-line serial interface

2-line serial interface slave address

A7	A6	A5	A4	A3	A2	A1	R/W
1	1	0	1	0	0	1	0

Writing to the device is accomplished by sequentially sending the device address D2_H, the dummy bytes (command code and the number of bytes), and the data bytes. This sequence is illustrated in the following tables:



2-line serial interface configuration command bitmap

The 2-line serial command bytes are used to control the output clock pairs (Y[0:9], \overline{Y} [0:9]). The output clock pairs are enabled after power up. During normal operation, the clock pairs can be disabled (set Hi-Z) or enabled (running) by writing the corresponding bit to the data bytes in the following tables:

Byte 0: Enable/Disable Register (H = Enable, L = Disable)

Byte 1: Enable/Disable Register (H = Enable, L = Disable)

BIT	PINS	INITIAL VALUE	DESCRIPTION	BIT	PINS	INITIAL VALUE	DESCRIPTION
7	3, 2	H	Y0, \overline{Y} 0	7	29, 30	H	Y8, \overline{Y} 8
6	5, 6	H	Y1, \overline{Y} 1	6	27, 26	H	Y9, \overline{Y} 9
5	10, 9	H	Y2, \overline{Y} 2	5	-	L	Reserved
4	20, 19	H	Y3, \overline{Y} 3	4	-	L	Reserved
3	22, 23	H	Y4, \overline{Y} 4	3	-	L	Reserved
2	46, 47	H	Y5, \overline{Y} 5	2	-	L	Reserved
1	44, 43	H	Y6, \overline{Y} 6	1	-	L	Reserved
0	39, 40	H	Y7, \overline{Y} 7	0	-	L	Reserved

PARAMETER MEASUREMENT INFORMATION

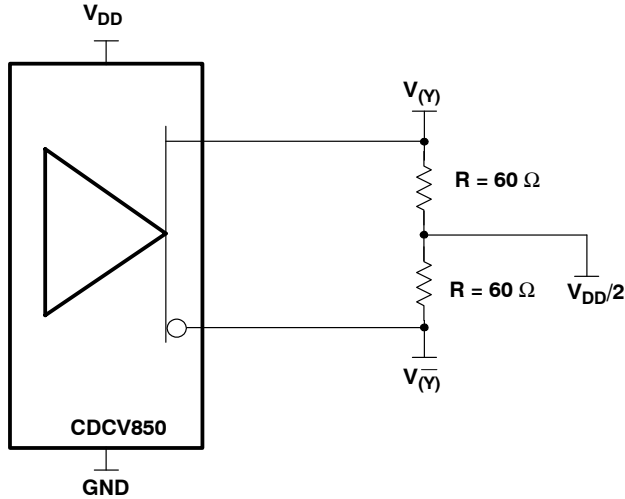


Figure 1. IBIS Model Output Load (used for slew rate measurement)

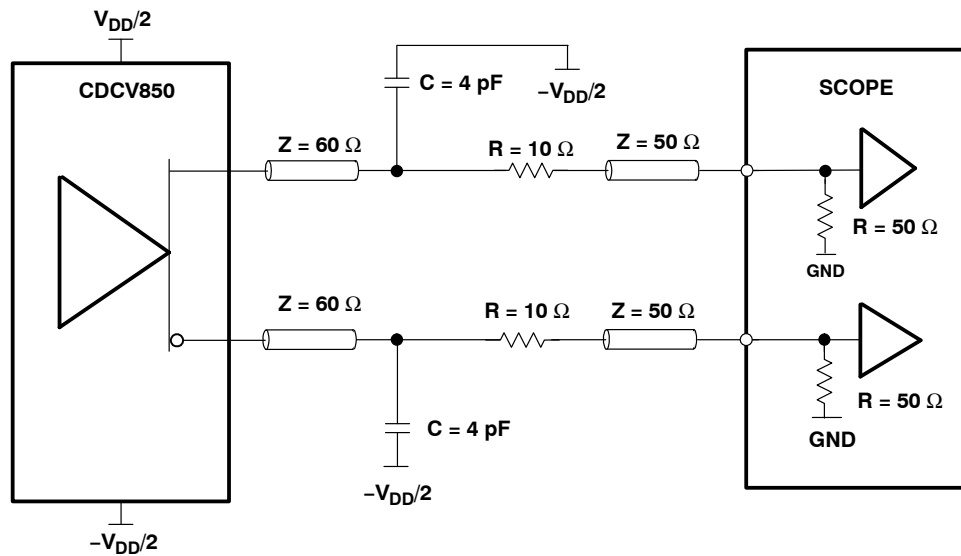


Figure 2. Output Load Test Circuit

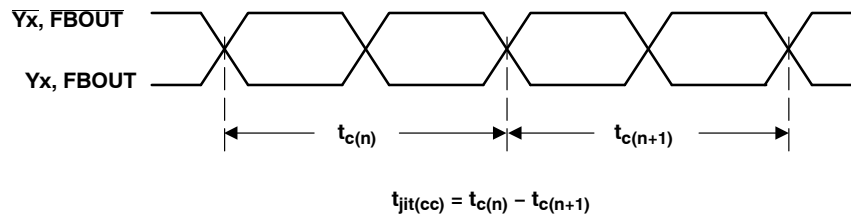
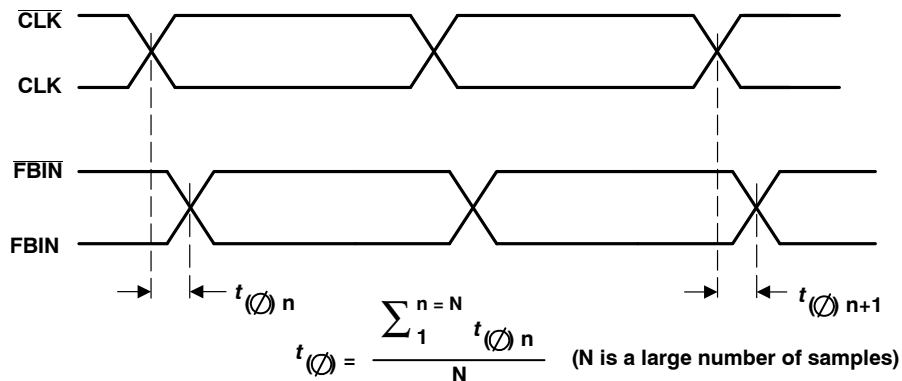


Figure 3. Cycle-to-Cycle Jitter

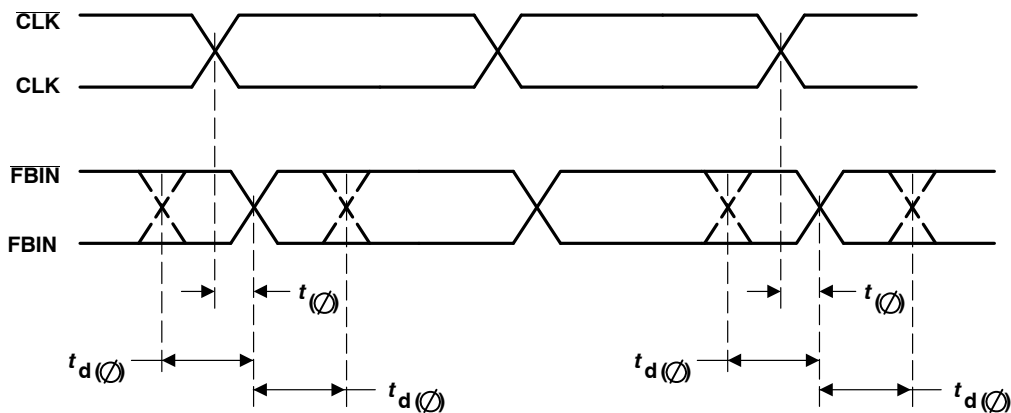
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PARAMETER MEASUREMENT INFORMATION



(a) Static Phase Offset



(b) Dynamic Phase Offset

Figure 4. Static Phase Offset

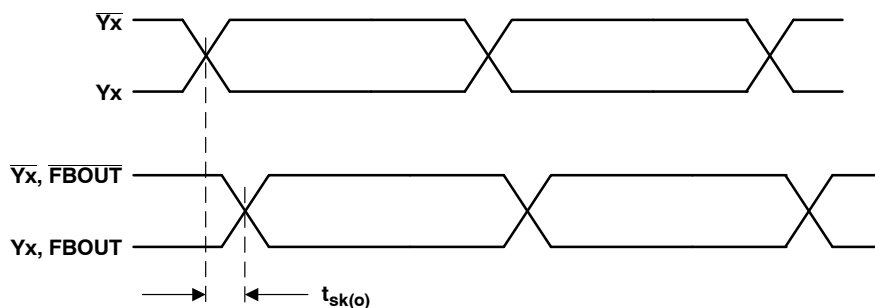


Figure 5. Output Skew

PARAMETER MEASUREMENT INFORMATION

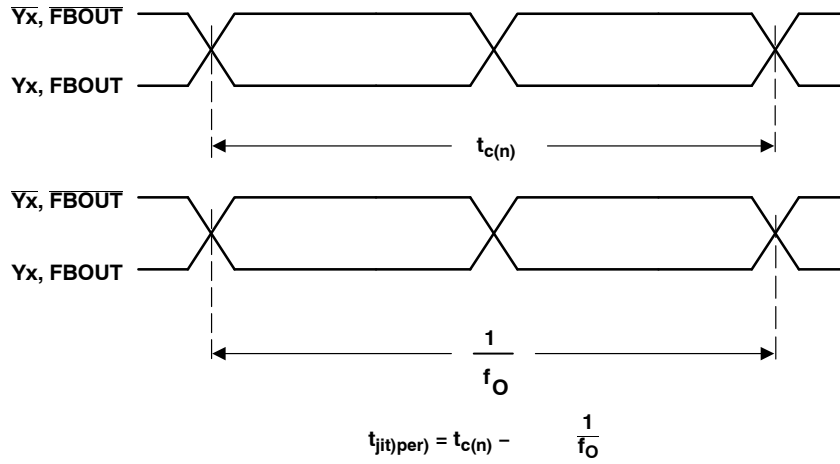


Figure 6. Period Jitter

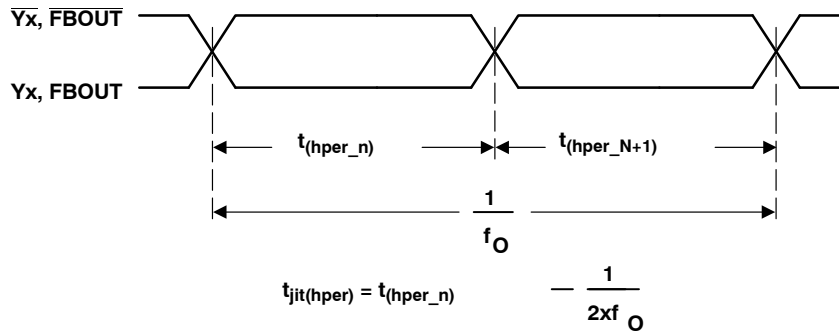


Figure 7. Half-Period Jitter

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PARAMETER MEASUREMENT INFORMATION

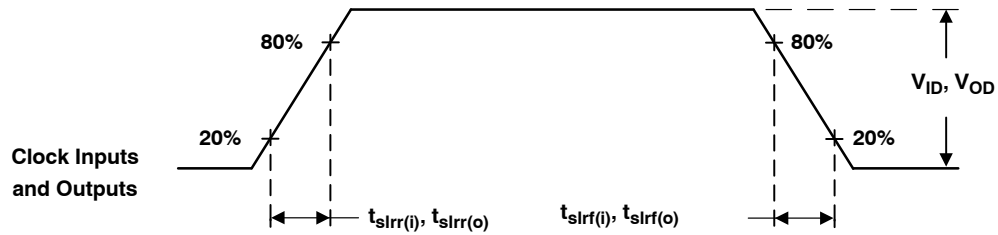


Figure 8. Input and Output Slew Rates

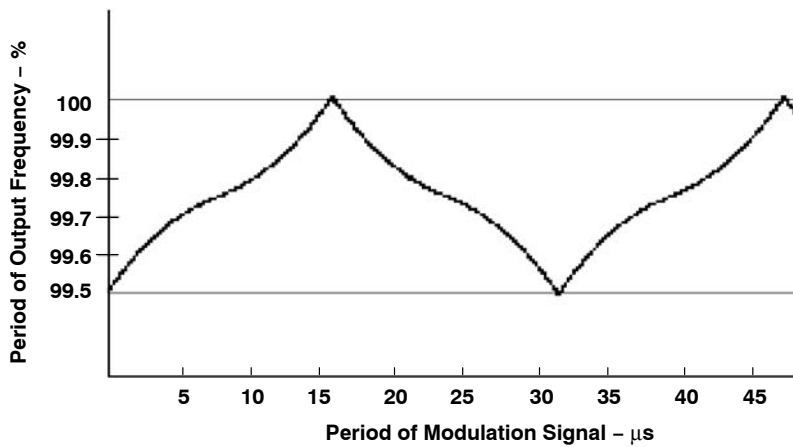
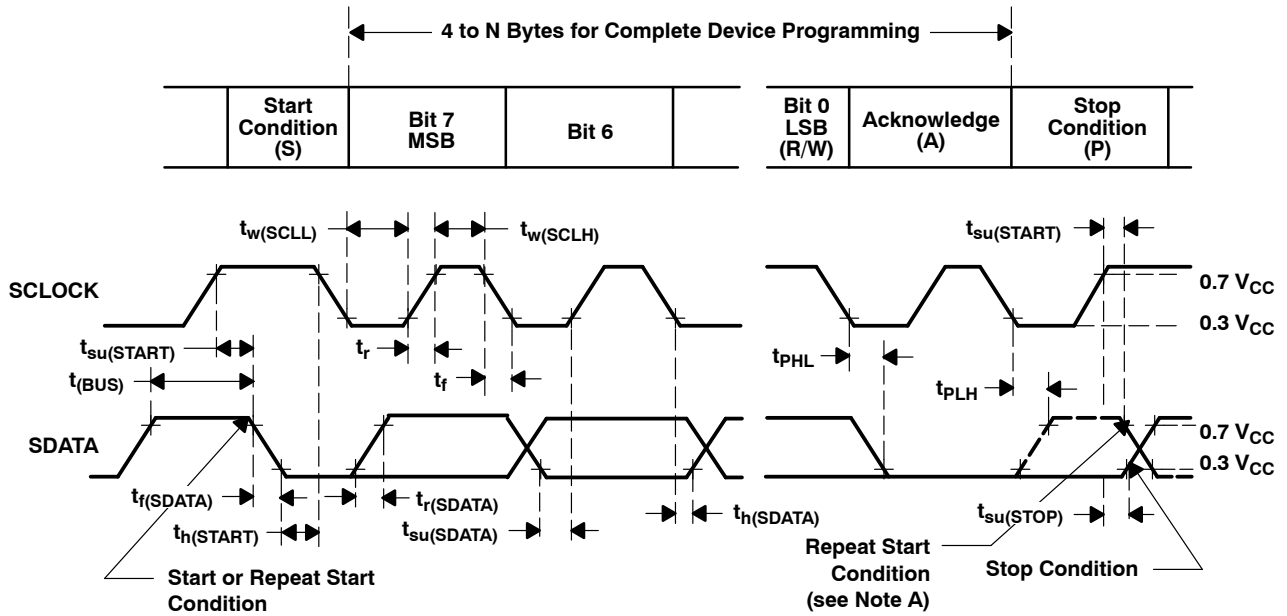
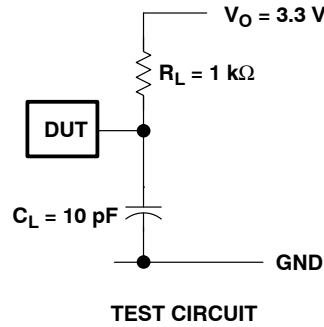


Figure 9. SSC Modulation Profile

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VOLTAGE WAVEFORMS

BYTE	DESCRIPTION
1	Slave Address
2	Common (Dummy Value, Ignored)
3	Byte Count = N
4	Data Byte 0
5 - N	Data Byte 1 - N

NOTE A: The repeat start condition is supported. If PWRDWN# is asserted SDATA will be set to off-state, high impedance.

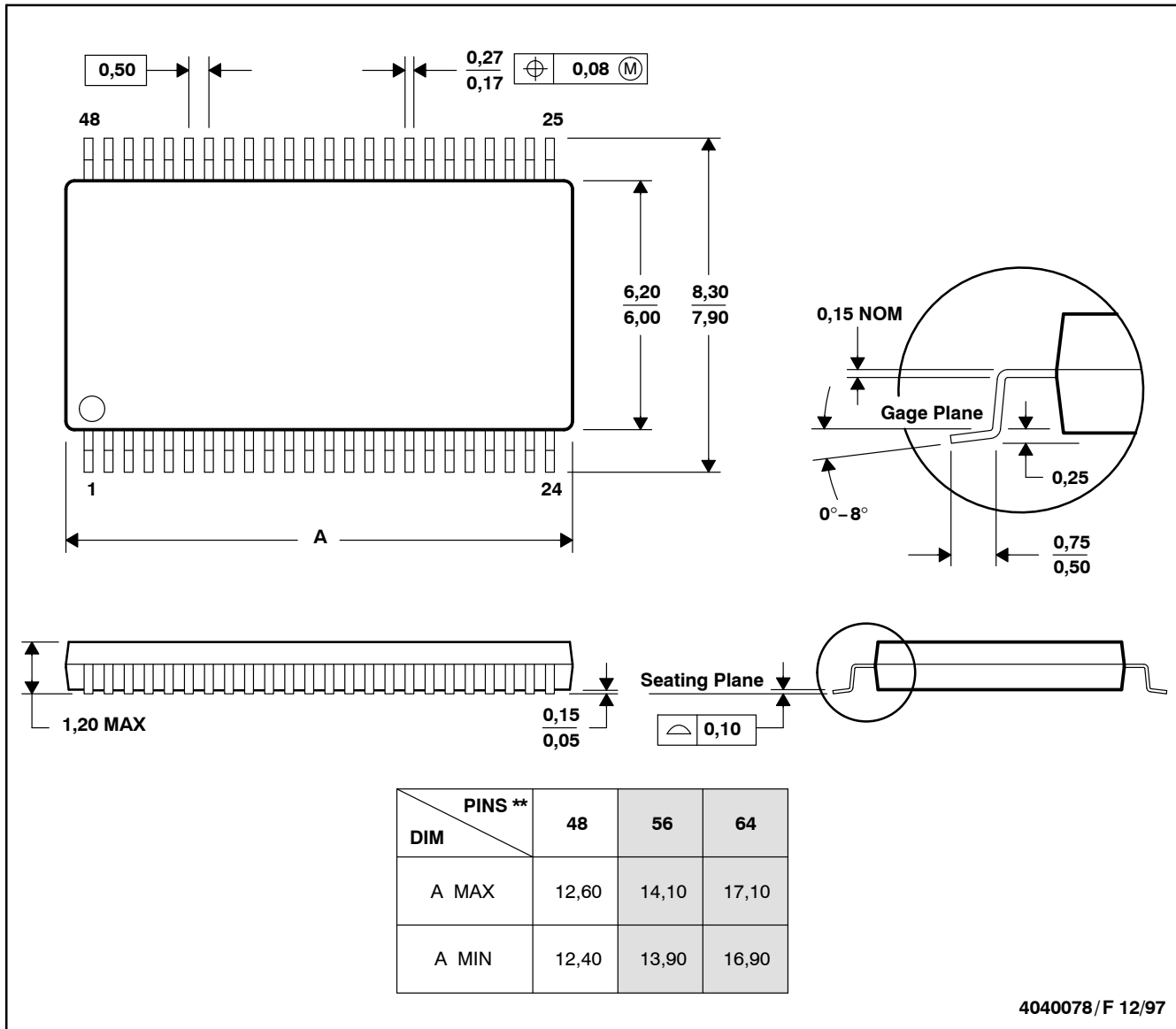
Figure 10. Propagation Delay Times, t_r and t_f

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MECHANICAL DATA

48 PINS SHOWN



- NOTES: B. All linear dimensions are in millimeters.
 C. This drawing is subject to change without notice.
 D. Body dimensions do not include mold protrusion not to exceed 0,15.
 E. Falls within JEDEC MO-153

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CDCV850DGG	ACTIVE	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCV850	Samples
CDCV850DGGG4	ACTIVE	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCV850	Samples
CDCV850DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCV850	Samples
CDCV850DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCV850	Samples
CDCV850IDGG	NRND	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCV850-I	
CDCV850IDGGG4	NRND	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CDCV850-I	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCV850DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCV850DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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